



TECHNICAL DATA SHEET

301

Heat Transfer Compound

General Description

301 heat transfer compound is a grease like silicone polymer, heavily filled with heat conductive material. This combination insures high thermal conductivity, low bleed, high temperature stability and high dielectric strength, the compound will not dry out, harden or melt even after longtime exposure to temperature up to 178°C. Service temperature ranges from -54°C to 178°C.

Recommended for use

It has widely used in electronic industry for mounting power transistor to chassis and heat sink for longer life.

Physical Data

Worked Penetration	:	260 - 340 Max.
Bleed 24 hrs. 200°C	:	1% Max.
Volume Resistivity	:	1 x 10 ¹⁵
Dielectric Constant	:	4.5
Evaporation 24 hrs. 200°C	:	1%
Thermal Conductivity BTU/Hr./Sq.Ft./Ft.	:	0.428